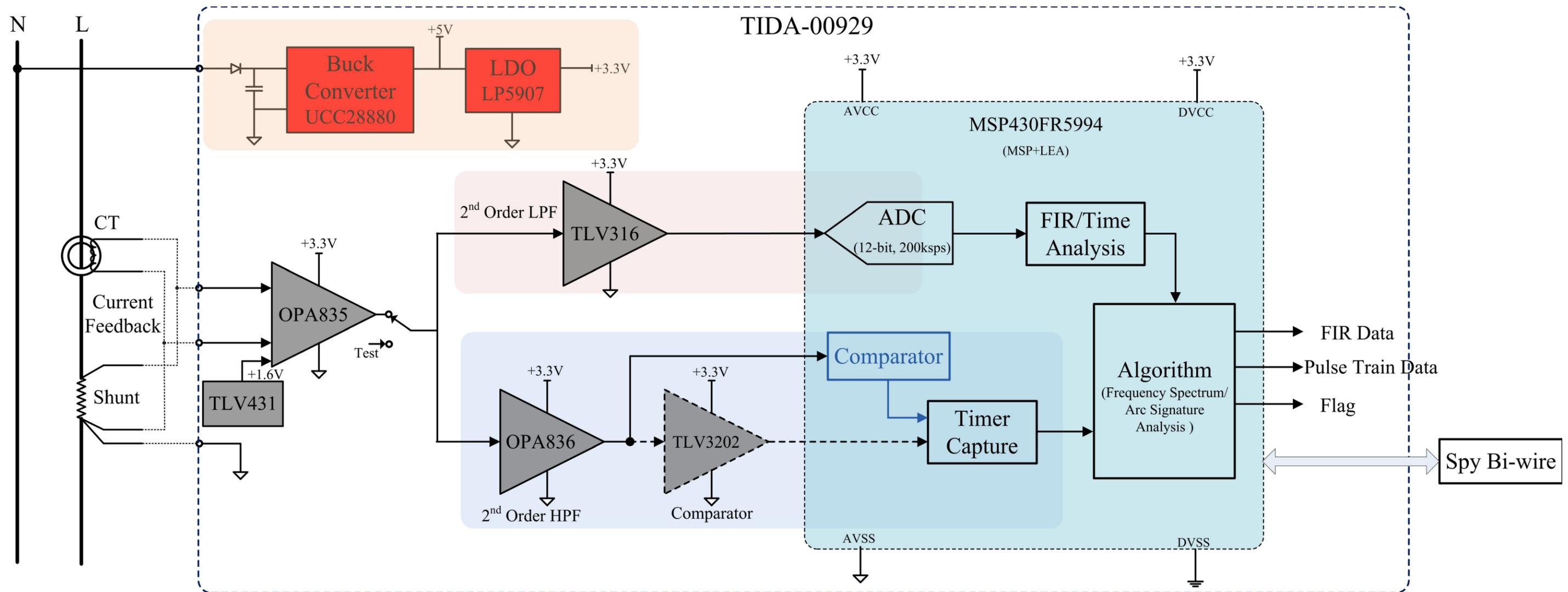
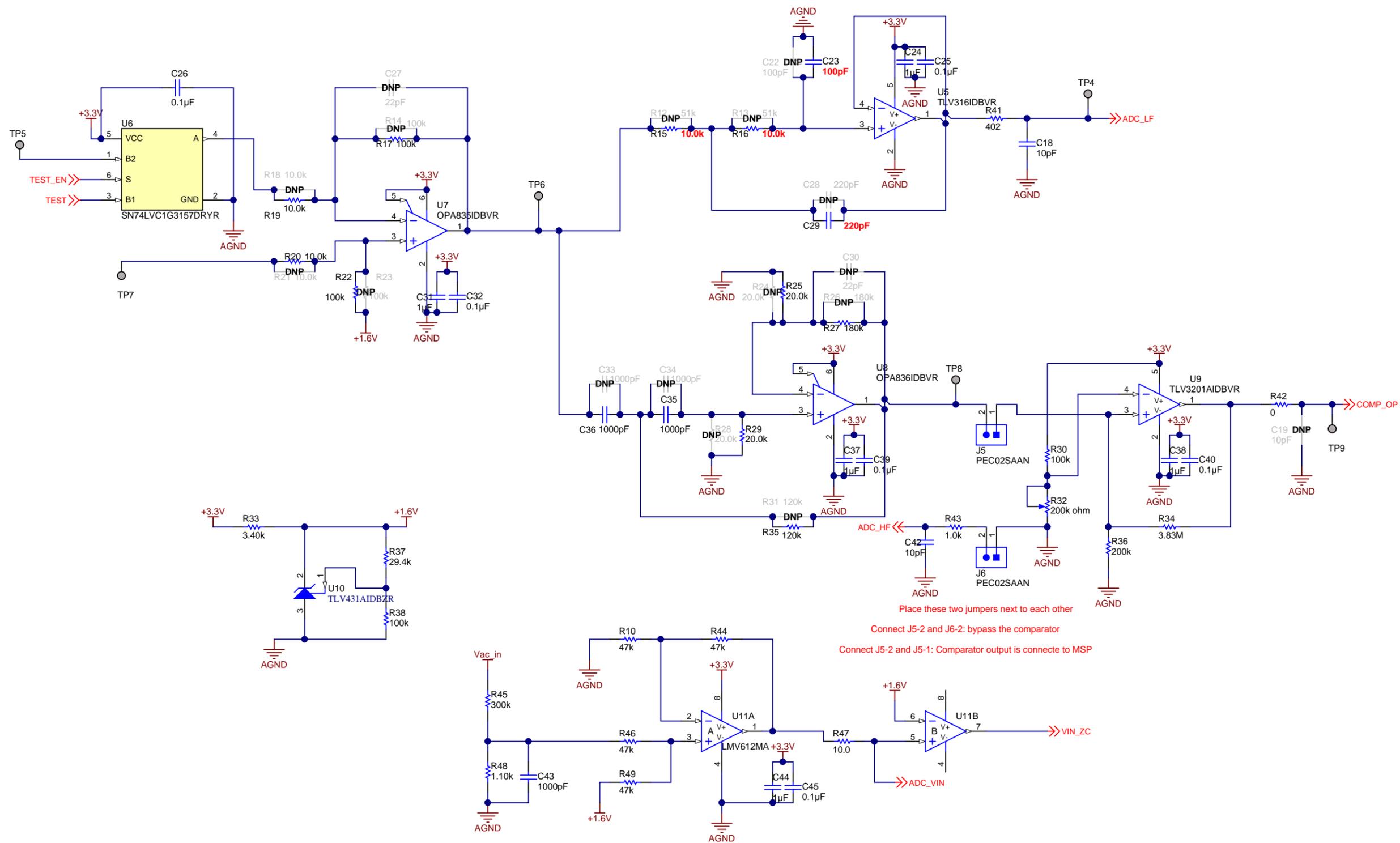


Revision History				
Rev	ECN #	Approved Date	Approved by	Notes
N/A	N/A	N/A	N/A	N/A



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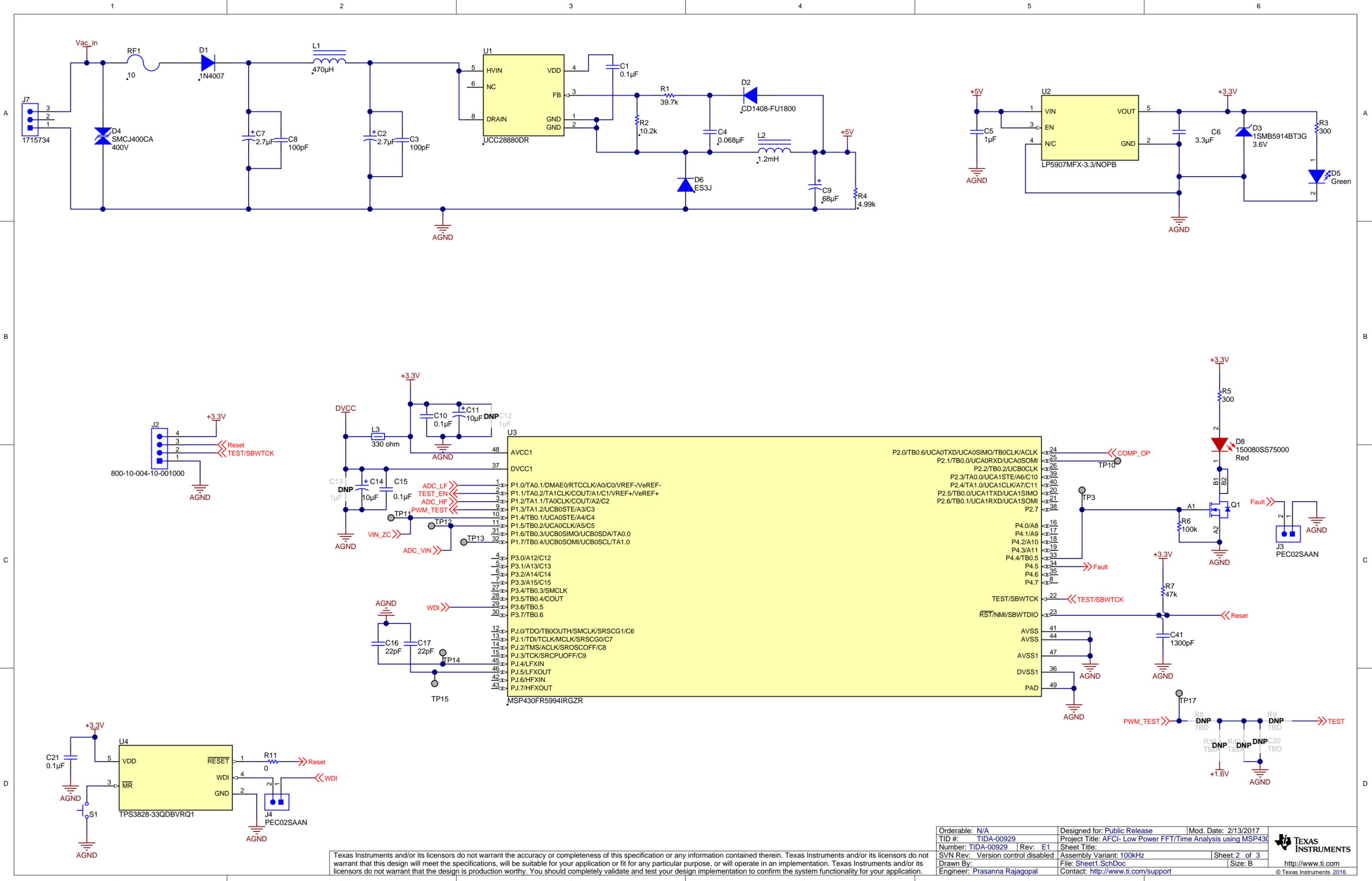
Orderable: N/A	Designed for: Public Release	Mod. Date: 2/10/2017	 http://www.ti.com
TID #: TIDA-00929	Project Title: AFCL- Low Power FFT/Time Analysis using MSP430	Sheet Title:	
Number: TIDA-00929	Rev: E1	Assembly Variant: 100kHz	
SVN Rev: Version control disabled	File: CoverSheet.SchDoc	Size: B	
Drawn By: Engineer: Prasanna Rajagopal	Contact: http://www.ti.com/support		



Place these two jumpers next to each other
 Connect J5-2 and J6-2: bypass the comparator
 Connect J5-2 and J5-1: Comparator output is connecte to MSP

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Number: TIDA-00929	Rev: E1	Assembly Variant: 100kHz	
SVN Rev: Version control disabled	File: Sheet2.SchDoc	Size: B	
Drawn By:	Engineer: Prasanna Rajagopal	Contact: http://www.ti.com/support	



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TID #: TIDA-00929	Project Title: AFCL- Low Power FFT/Time Analysis using MSP430	Sheet: 2 of 3	
Number: TIDA-00929	Rev: E1	Size: B	
SVN Rev: Version control disabled	Assembly Variant: 100kHz		
Drawn By:	File: Sheet1_SchDoc		
Engineer: Prasanna Rajagopal	Contact: http://www.ti.com/support		

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TID #: TIDA-00929	Project Title: AFCL- Low Power FFT/Time Analysis using MSP430		
Number: TIDA-00929	Rev: E1	Sheet Title:	
SVN Rev: Version control disabled	Assembly Variant: 100kHz	Sheet: 2 of 3	
Drawn By:	File: BlankSheet.SchDoc	Size: B	
Engineer: Prasanna Rajagopal	Contact: http://www.ti.com/support		



You should delete the nylon screws/standoffs and/or the bumpers as needed for your design (or substitute other parts from Hardware.IntLib). Bumpers are cheaper, but provide less clearance.

Deleting anything else from this page may result in your EVM submission being rejected (until you add them back).

Update the Label Text in the Label Table as needed for each Assembly Variant.

You should delete this note too.



PCB Number: TIDA-00929
PCB Rev: E1

PCB LOGO
Texas Instruments

PCB LOGO
Pb-Free Symbol

PCB LOGO
FCC disclaimer



LBL1
PCB Label
Size: 0.65" x 0.20"

ZZ1
Label Assembly Note
This Assembly Note is for PCB labels only

ZZ2
Assembly Note
These assemblies are ESD sensitive, ESD precautions shall be observed.

ZZ3
Assembly Note
These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.

ZZ4
Assembly Note
These assemblies must comply with workmanship standards IPC-A-610 Class 2, unless otherwise specified.

Variant/Label Table	
Variant	Label Text
001	ChangeMe!
002	ChangeMe!

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TID #: TIDA-00929	Project Title: AFCL- Low Power FFT/Time Analysis using MSP430		
Number: TIDA-00929	Rev: E1	Sheet Title:	
SVN Rev: Version control disabled	Assembly Variant: 100kHz	Sheet: 3 of 3	
Drawn By: Prasanna Rajagopal	File: EVM_Hardware.SchDoc	Size: B	
Engineer: Prasanna Rajagopal	Contact: http://www.ti.com/support		

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